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				1	
PARTING DIN SI	nnal har_hi	is 61, mal	e connector	RoHS -	Soldering instructions
DIN 31	ynal nai-bl	12 04 11101		compliant C 7430	The connectors should be protected when being soldered in a dip, flow or film soldering bath. Otherwise, they might become contaminated as a result of soldering operations or deformed as a result of overheating.
eneral information	:	-	:		 ─ (1) For prototypes and short runs protect the connectors with an industrial adhesive tape, e.g. Tesaband 4331 (www.tesa.de).
					Cover the underside of the connector moulding and the adjacent parts of the pcb as well as the open sides of the connector. The
lesign	IEC 61076-4-113				will prevent heat and gases of the soldering apparatus from damaging the connector. About 140 + 5 mm of the tape should
o. of contacts	max. 160				suffice.
ontact spacing	2,54mm	- · · · · · · · · · · · · · · · · · · ·			— (2) For large series a jig is recommended. Its protective cover with a fast action mechanical locking device shields the connectors
est voltage	1000V				from gas and heat generated by the soldering apparatus. As an additional protection a foil can be used for covering the parts
ontact resistance		max. 20m0hm for rows a, b, c max. 30m0hm for rows d, z			that should not be soldered.
sulation resistance	· · · · · · · · · · · · · · · · · · ·	min. 10°0hm			-
orking current		1A at 70°C (see derating diagram) -55°C +125°C			Cross section of solder pins
emperature range ermination technology	-55°C +125°C				— Recommended plated hole diameter: Ø 1± 0,1mm
ermination reciliotogy	Sounei	minimum distan	rows a, b, c	rows d, z	- The same of th
Clearance & creepage		clearance	1,2mm	1,2mm	
	between 2 ro	ws creepage	1,2mm	1,2mm	
	between 2	clearance	1,2mm	1,0mm	0.49+0.06 0.6+0.05
	contacts in a		1,2mm	1,0mm	
sertion and withdrawal force	max. 160N		,		0,8_0,03
PCB thickness min. 1,6mm					
Mating cycles acc. to performance level, see table below				0,025	
UL file E102079				0,52_	
oHS – compliant	Yes				_ ' '
eadfree	Yes				Derating diagram acc. to IEC 60512-5 (Current carrying capacity)
nsulator material					The current carrying capacity is limited by maximum temperature of materials for inserts and contacts
 1aterial	LCP (Liquid Cristal Polymer)				_ including terminals ≤ 1,5
olour	nature			,	The current capacity curve is valid for continuous,
L classification	· · · · · · · · · · · · · · · · · · ·				I non interrupted current todaed contacts of connectors
Material group acc. to IEC 60664-1 IIIa (175 < CTI < 400)				when simultaneous power on all contacts is given, without exceeding the maximum temperature. Control and test procedures according to DIN IEC 60512-5	
ontact material					─ With selective loading higher currents can be transmitted.
ontact material	Copper alloy				— The requirements according to VITA 1.7 are futilitied. 0 20 40 60 80 100 120 14
lating termination zone	Sn over Ni				Temperature [°C]
Plating contact zone acc. to performance level, see table below				_	
					_
					_
	mating c	mating cycles plating contact zone			
performance level	acc. to	complementary : to IEC 61076-4-113	row d,z	row a,b,c	
1	500		Au over Ni	Au over PdNi over Ni	<u>_</u>
2	250		Au over Ni	Au over PdNi over Ni	All Dimensions in mm Scale Free size tol. Ref.
3		50	Au over Ni	Au over PdNi over Ni	All Dimensions in mm Scale Original Size DIN A3 1:1 Free size tol. Ref. Sub.
Au30		500		inch) Au over Ni	All rights reserved Created by STORCK Inspected by Standardisation Date State
Au50 500 min. 1,27µm (50µinch) Au over Ni				Department of the Control of the Con	
Standard	plating options highlight	ed in bold, other plati	ng options are available or	n request.	HARTING Electronics GmbH Title DIN Signal har-bus 64 male connector Type DC Number 0.20112.00.201 Rev. D
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